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Characterization of boron carbide thin films fabricated by plasma enhanced chemical vapor deposition from boranes

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We have fabricated boron carbide thin films on Si(111) and other substrates by plasma-enhanced chemical-vapor deposition (PECVD). The PECVD of boron carbides from nido-cage boranes, specially nido-pentaborane(9) (B₅H₉), and methane (CH₄) is demonstrated. The band gap is closely correlated with the boron to carbon ratio and can range from 0.77 to 1.80 eV and is consistent with the thermal activation barrier of 1.25 eV for conductivity. We have made boron carbide by PECVD from pentaborane and methane that is sufficiently isotropic to obtain resistivities as large as 10¹⁰ Ω cm at room temperature. This material is also shown to be suitable for photoactive p-n heterojunction diode fabrication in combination with Si(111).

I. INTRODUCTION

A wide variety of techniques have been employed to make boron-rich carbides. Most of these techniques result in boron carbides with only a limited range of compositions as summarized in Fig. 1. Employing alkanes and heavy borane cage molecules, as noted in preliminary papers, is a relatively safe and effective alternative for fabricating boron carbide thin films. The use of plasma-enhanced chemical-vapor deposition (PECVD) provides a means for fabricating boron carbide thin films without resorting to high temperatures (>1000 °C) and pressures (>50 Torr) that have been required to fabricate boron carbides. Typical CVD deposition experiments have employed BC₃ and hydrocarbons such as methane, BC₃+CCl₄, BBr₃ and methane, or B₂H₆ and methane. We have previously shown that nido-decaborane(14) (B₁₀H₁₄) was a suitable source for the deposition of boron, boron nitride films, and is now widely used for the boron doping of silicon. Lighter boranes like diborane (B₂H₆) have been explored but are extremely hazardous resulting in the search for safer boron source alternatives such as borontrioxide (B₂O₃). Boron carbide films have also been made by sputtering boron carbide targets. A few examples of boron carbide from carboranes do exist but are limited in scope.

The work undertaken to assess the properties of boron carbides has been controversial despite the considerable efforts to theoretically model and fabricate these materials. In this paper, we provide some indication of the electronic structure and optical properties of boron carbides fabricated by PECVD.

II. EXPERIMENT

A. Film fabrication

Nido-decaborane(14) and nido-pentaborane(9) were used as source compounds with methane. Nido-decaborane(14) was an air-stable white crystalline solid with a vapor pressure of several Torr at room temperature and obtained from the U.S. Army at Redstone Arsenal, vacuum sublimed and stored in vacuo prior to use. Nido-pentaborane(9) was from our laboratory stock. The identity and purity of compounds were determined by nuclear magnetic resonance (NMR), Fourier transform infrared spectroscopy (FTIR), and mass spectral measurements. The sample cell was heated to increase the vapor pressure of nido-decaborane(14) (B₁₀H₁₄) for the experiments with B₁₀H₁₄. Deposition of boron nitride films, was previously shown that nido-decaborane(14) (B₁₀H₁₄) was a suitable source for the deposition of boron, boron nitride films, and is now widely used for the boron doping of silicon. Lighter boranes like diborane (B₂H₆) have been explored but are extremely hazardous resulting in the search for safer boron source alternatives such as borontrioxide (B₂O₃). Boron carbide films have also been made by sputtering boron carbide targets. A few examples of boron carbide from carboranes do exist but are limited in scope.

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thin film, total pressure of reactants, applied power, and deposition time were fixed for the entire experiment, approximately 400 °C, 50 mTorr, 20 W (maximum power density of 3.7 W/cm²) and 30 min, respectively.

B. Film characterization

The compositions of thin films were determined by a Perkin Elmer Auger electron spectrometer equipped with a cylindrical mirror analyzer (CMA). The system was calibrated using the boron 179 eV line and the carbon 272 eV line of a B& standard combined with Ar⁺ ion sputtering to provide a depth profile of the composition. The thicknesses of the films were from 0.1 to 1.0 μm thick depending upon reactants and their partial pressure ratios. Auger profiling was limited by a mask to a 2 mm square to reduce the thickness measurement error. The depth of this sputtered square was measured using a Sloan Dektak profilometer. Auger profile data was then calibrated to this measured depth.

The optical absorption spectra of the different composition films on the glass produced from *nido-*decaborane(14), B₁₂H₁₄ and *nido-*pentaborane(9), B₅H₉. For each deposition, the correct partial pressures for each source mixture were attained and stabilized. A plasma was then struck and held for the duration of the film deposition. Using this procedure, and provided that the source compounds were pure (contained little admixture of contaminants), it was relatively easy to fabricate pure boron carbide films.

Some oxygen was found upon exposing the films to air, particularly for the films fabricated from *nido-*decaborane(14). In general, the films fabricated using *nido-*decaborane(14) as the boron source material were found to be less compositionally uniform than films fabricated from *nido-*pentaborane(9). Because the film stoichiometry and compositional uniformity could be more easy to control using *nido-*pentaborane(9) than with *nido-*decaborane(14), this paper largely reflects films made with *nido-*pentaborane(9).

Figure 2 shows an Auger electron spectra for a typical film. Little or no impurities were observed upon analysis of the Auger electron spectra for films deposited from pentaborane and methane. By sputtering the films at a fixed rate, film composition profiles were generated. A typical elemental composition profile is shown in Fig. 2 for a boron carbide film deposited on Si(111). Hydrogen is the only impurity in the source gases but elemental analysis of very thick films indicates the hydrogen impurity level is much less than 6%.

Defining the partial pressure ratio as the ratio of partial pressures for the source vapor pentaborane containing boron and the source vapor methane containing carbon, we find a correlation between partial pressure ratio and the boron to carbon ratio for the resulting film, as shown in Fig. 3. Systematic errors occur as a result of sample annealing temperature, plasma power and total pressure that are not fully understood but for a single set of parameter conditions the correlation between partial pressures and film composition can be easily identified (as seen in the
insert to Fig. 3). The relationship is not a proportional relationship even when available boron or carbon atom numbers are considered. Extreme partial pressure ratios produce only moderate film composition ratios. For instance, a drastic reduction in the pentaborane source partial pressure produces only a moderate decrease in measured boron percent in the film. Likewise, a drastic increase in pentaborane source partial pressures produces a moderate increase in measured boron percent for the very boron rich films. Large differences in the boron to carbon content in the film are still attainable and compared well with boron carbide films made by other methods as seen in Fig. 1. Pure boron or carbon films could, of course, be produced by using only borane or hydrocarbon sources, respectively.

The lack of proportionality in controlling film composition by relative partial pressure changes suggest that many surface reactions may occur including carborane cluster formation initiated during the deposition process or gas phase plasma initiated chemistry. Adsorption studies of simple carboranes on boron carbide films and on Si(111) indicates that the decomposition process of a carborane can be very complex. For the adsorption and dissociation of nido-diethyl-2,3-dicarbahexaborane on Si(111) (Ref. 56) and on boron rich surfaces, the formation of boron rich surface complexes prior to dissociation can be clearly observed even for film deposition and molecular dissociation initiated by incident radiation. It is difficult to exclude the possibility that plasma mediated gaseous species affect the relationship between partial pressure and film composition. It is well known that pentaborane and hexaborane species are a thermodynamic sink in the thermolysis and photolysis of light boranes. Other similar thermodynamic carborane sinks also may exist. The results obtained with PECVD of boron carbide using the lighter boranes indicates that our results may be applicable to PECVD fabrication with many boranes and carboranes.

X-ray diffraction studies of thicker films of boron carbide (\(>1 \mu m\)) deposited on Si(111) do exhibit boron carbide diffraction features as seen in Fig. 4. The diffraction lines are broad in the range \(42^\circ<2\theta<50^\circ\). Calculated \(d\)-spacings values corresponding to the doublet broad peaks are 2.03 and 1.87 Å. The isotropic boron carbide phase produced by PECVD may be easily distinguished from silicon substrate. The \(d\)-spacings values are smaller than the reported value (2.74 Å) for single crystalline \(B_2C\), but are very close to the nearest neighbor bond lengths expected for this material. The films do exhibit diffraction patterns more characteristic of microcrystalline or amorphous films than crystalline boron carbide. Boron-rich materials, particularly from the \(\alpha\)-rhombohedral polytype, are
The conductivity of boron carbides has been previously studied by Emin and co-workers, Zuppiroli and co-workers, and others. As with rhombohedral boron, the primary mode of conduction is generally thought to be by hopping. It has been reported that the magnitude of the electrical conductivity varies considerably with sample preparation and material purity. While our conductivity is much smaller than reported for boron carbide samples, it has been noted that free carbon will dramatically enhance the dc conductivity. Thus, our conductivity measurements suggest that in spite of the large carbon concentrations in our PECVD fabricated films there is little free carbon. This evidence for more uniform isotropic films is also supported by the thermal activation barrier. Indeed, the magnitude of our conductivities is seen for other boron carbides only at temperatures well below room temperature.

The calculated thermal activation barrier for our PECVD fabricated boron films is 1.25 eV and is virtually independent of composition. While Emin and co-workers observe conductivities that are weakly dependent on composition, their conductivities are much higher (as plotted in Fig. 5) and their thermal activation barriers are much smaller (0.14 ± 0.01 eV). Werheit and de Groot also find little dependence of the composition on conductivity and observe a thermal activation energy that is also very small (0.16 eV). The activation barriers measured by Wood, and Zuppiroli and co-workers are somewhat larger with values of 0.3–0.4 eV and conductivities only weakly depend upon coverage. The magnitude of our thermal conductivity activation barrier is much closer to that of pure boron as measured by Morita and Yamamoto (0.51–0.58 eV), Neft and Seiler (0.42 eV), Niemyski and Zawadzki (1.05–1.16 eV) (Ref. 87) and others (1.35–1.45 eV) (Refs. 86 and 88–97). The conductivities of PECVD fabricated boron carbide, for the most part, also are consistent with the magnitude of the conductivities measured for pure boron. Thus, the conductivity suggests that even for our most carbon rich films, there is little or no free carbon unlike other boron carbides. For the boron rich boron carbides, our PECVD fabricated boron carbide is more easily reconciled with the results obtained for pure boron than boron carbides fabricated by other methodologies.

B. Conductivity

The dark electrical conductivity was measured for boron carbide films that spanned a composition range from 4.7 to 19.0 boron to carbon ratio, for temperatures from room temperature to 100 °C. The electrical conductivity is seen to vary exponentially with reciprocal temperature, as seen in Fig. 5. As seen in the insert to Fig. 5, there is little variation in the conductivity as a function of composition. While the conductivities in this composition range are observed to be very small ~10^{-4} to ~10^{-10} Ω^{-1} cm^{-1}, illuminating the samples with visible light is not seen to dramatically affect the conductivity (changes by more than a factor of 4 have not been observed), and we conclude that the conductivity is generally insensitive to visible light.

C. The band gap

Over the composition range from 2.4 to 50 boron to carbon ratio the optical band-edge absorption was measured for different boron carbide composition. The optical band gap was obtained from this data as shown in Fig. 6, as is the accepted practice. For the highest carbon concentration, the lowest band gap (0.77 eV) was obtained and the band gap could be varied from 0.77 to 1.80 eV. The band gap is seen to be a closely related property of composition of our boron carbide films as seen in Fig. 7. The band gap for boron-rich films obtained by us is in good agreement with the band gaps determined by Klein (1.5–1.6 eV) (Ref. 99) and Horn (1.6–2.0 eV) (Ref. 97) and are somewhat larger than the band gap estimated by others.
(1.34 eV). The absorption edge derived band gap is seen to be consistent with the band gap obtained from photoluminescence spectra. Photoluminescence spectrum exhibits a peak at 1.76 eV (Fig. 8) for B₆₀C, is consistent with an absorption edge derived band gap of 1.77 eV.

Comparison of these measured band gaps at room temperature with theory (Table I) shows that our band gaps, in general, are smaller than expected. To reconcile the band gap we measure with the calculated indirect band gaps, one notes that band gaps calculated by density functional theory are often wrong for zinc blende and diamond structure semiconductors. We, thus, can reconcile the calculated results of Kleinman and co-workers to our experimental results. It is also important to note that there exist two icosahedral boron carbide structures. The one fabricated in PECVD may have a somewhat different structure that the one commonly fabricated. This may account for some of the differences in conductivity and band gap from other bulk boron carbides.

TABLE I. Comparison of various boron and boron carbide film band gaps. Parentheses indicate an estimated value, not direct measurement.

<table>
<thead>
<tr>
<th>Composition</th>
<th>Band gap (eV) (theory)</th>
<th>Band gap (eV) (experiment)</th>
</tr>
</thead>
<tbody>
<tr>
<td>B₁₂C₃</td>
<td>3.05 b 2.80 b</td>
<td>... ...</td>
</tr>
<tr>
<td>B₁₂</td>
<td>1.78 c 1.43 d e</td>
<td>... ...</td>
</tr>
<tr>
<td>B₁₀</td>
<td>2.17 f 1.70 f</td>
<td>... ...</td>
</tr>
<tr>
<td>Pure boron</td>
<td>...</td>
<td>1.4-2.1 i 1.54 h</td>
</tr>
<tr>
<td>B₆₀C</td>
<td>...</td>
<td>1.6-2.0 j 1.34 j 1.5-1.6 k</td>
</tr>
<tr>
<td>B₉₀C</td>
<td>...</td>
<td>(2.1 ± 0.2) ± 1.76-1.80 a</td>
</tr>
<tr>
<td>Pure C</td>
<td>...</td>
<td>1.60 j 1.00 ± 0.8 ±</td>
</tr>
</tbody>
</table>

*This work.  
See Ref. 45.  
See Ref. 43.  
See Ref. 44.  
See Ref. 50.  
See Ref. 41.  
See Ref. 40.  
See Ref. 103.  
See Refs. 82, 97, and 104.  
See Ref. 98.  
See Ref. 99.  
See Ref. 100.  
See Ref. 77.
FIG. 9. I-V characteristic curves of B$_4$C/Si(111) p-n heterojunction diode. I-V curves were obtained for illuminated (--) and dark (---) samples indicating the light sensitivity of these diodes. Forward bias current plotted in log scale shows that the current does not increase exponentially (left-top inset). Curves plotted on an expanded scale clearly show hysteresis (right-bottom inset).

On the other hand, the band gap we determine for our PECVD fabricated samples shows a greater dependence upon composition than is indicated by some measurements,"

FIG. 10. Threshold or onset voltage for forward biased current flow of mesa geometry p-n boron carbide/Si(111) heterojunction diodes as a function of boron carbide film thickness. The figure shows the quantitative differences between illuminated (---) and dark (---) samples as a function of B$_4$C film thickness.

D. Charge depletion and boron carbide/Si(111) heterojunction diodes

Since we have ascertained that boron carbide made by PECVD has a large band gap, we have tested the postulate that boron carbide has few carriers (as indicated by the low conductivity and other measurements) by fabricating heterojunction diodes with Si(111). As seen in Fig. 9, boron carbide makes an excellent p-n diode with n-type silicon doped to a 7 x 10$^{14}$/cm$^2$ (moderate) doping level. This is not surprising since boron carbide is generally considered as a p-type material and boron is a common p-type dopant of silicon.$^{34-37,105}$

The absence of an exponential increase in current versus applied forward voltage (as seen in the inset to Fig. 9) is consistent with a high resistivity material. The hysteresis that appears in the I-V traces, shown in Fig. 9, has also been observed for other heterojunction diodes (ZnSe/ZnCdSe) and has been interpreted as an effective resistor in series with a diode.$^{106}$ Both the hysteresis of the I-V curve and the deviation from exponential behavior are indicative of the high resistivity of boron carbide. Other similar high resistivity diodes have been fabricated out of unconventional materials such as diamond.$^{107}$

Unlike the pure boron carbide material, the heterojunction is seen to be strongly photoactive. Visible light is seen to increase the current in both the forward and reverse bias directions, but the effect of light is most pronounced in the forward direction, as seen in Fig. 9. This is consistent with the formation of a space-charge bilayer at the B$_4$C/Si(111) interface. Given the very low conductivity of boron carbide, we would anticipate that the depletion layer would be quite large. Using the threshold of forward current flow in the analog I-V plot as a figure of merit, we have determined that increasing the boron carbide film thickness of B$_4$C has a dramatic effect on the heterojunction I-V characteristics as seen in Fig. 10. This is consistent with the low carrier concentration in boron carbide.

From the thickness dependence, we can estimate space-charge depletion/enrichment extends into the boron carbide layer more than 1 $\mu$m. Si(111) more highly doped
The lower conductivities may be a consequence of the reduction of free carbon as may occur with other fabrication techniques. Graphitic carbon precipitates accounting for much as 2% to 3% of the material could lead to drastically enhanced conductivities particularly at grain boundaries. Given the lack of information of the various microstructures, the differences between PECVD boron carbide and other boron carbides cannot be unequivocally determined. Heterogeneous distribution of composition is indicated for the crystalline boron carbides by some studies, but not all. The films made by PECVD of borane, by virtue of their low carrier concentration, uniformity and readily formed space-charge layers (adjustable by either changing film thickness or boron carbide composition) are demonstrated to make photosensitive p-n heterojunction diodes.

VI. CONCLUSION

Boron carbide fabricated by PECVD exhibits vastly reduced conductivities over boron carbide fabricated by other methods. We find that increasing carbon concentration reduces the band gap consistent with models proposed by Werheit and co-workers and the band gap can be correlated with composition. The low carrier concentration, uniformity and readily formed space-charge layers (adjustable by either changing PECVD boron carbide and other boron carbides over boron carbide fabricated by other methods. We find that increasing carbon concentration reduces the band gap consistent with models proposed by Werheit and co-workers and the band gap can be correlated with composition. The low carrier concentration, uniformity and readily formed space-charge layers (adjustable by either changing film thickness or boron carbide composition) are demonstrated to make photosensitive p-n heterojunction diodes.

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